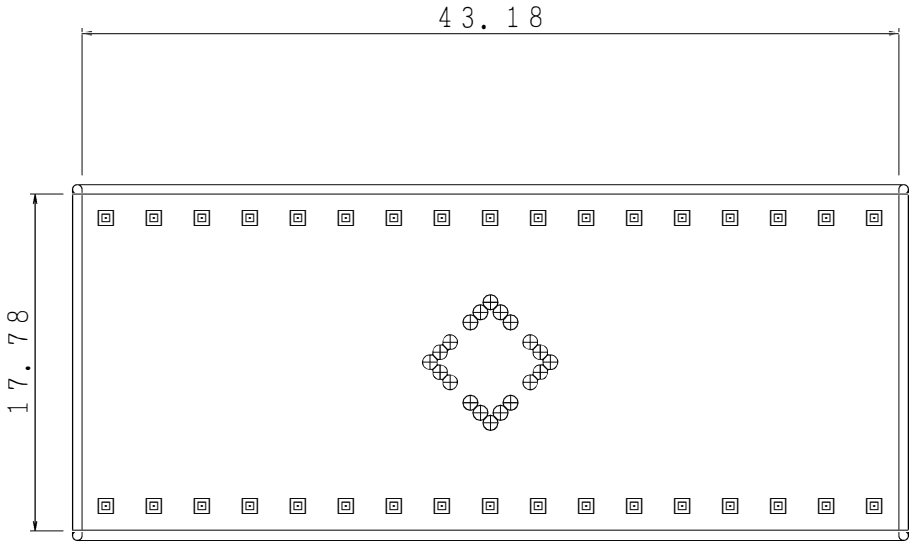
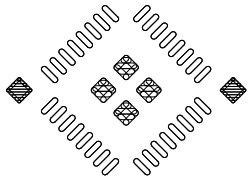
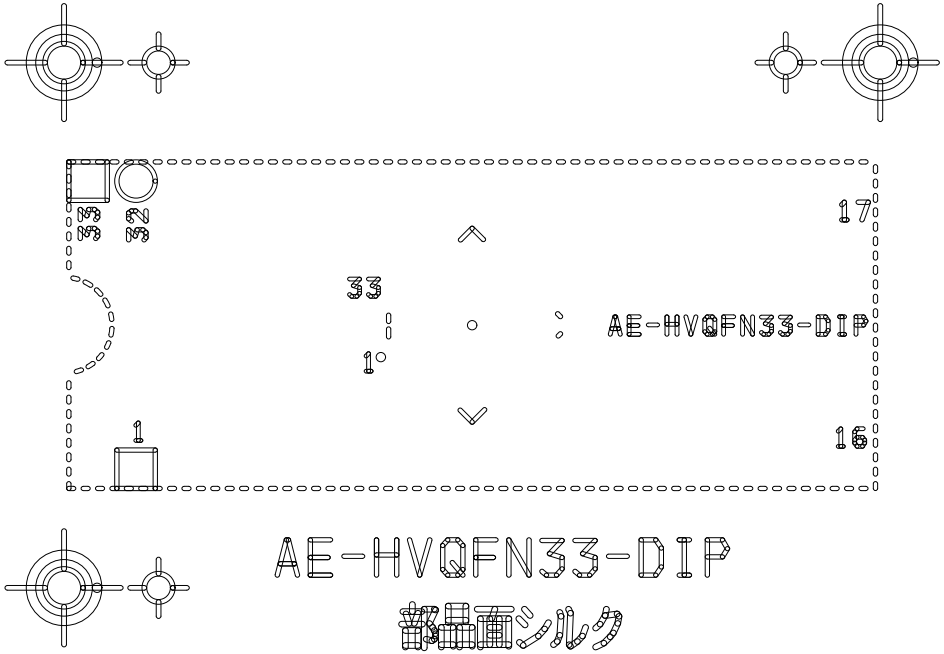
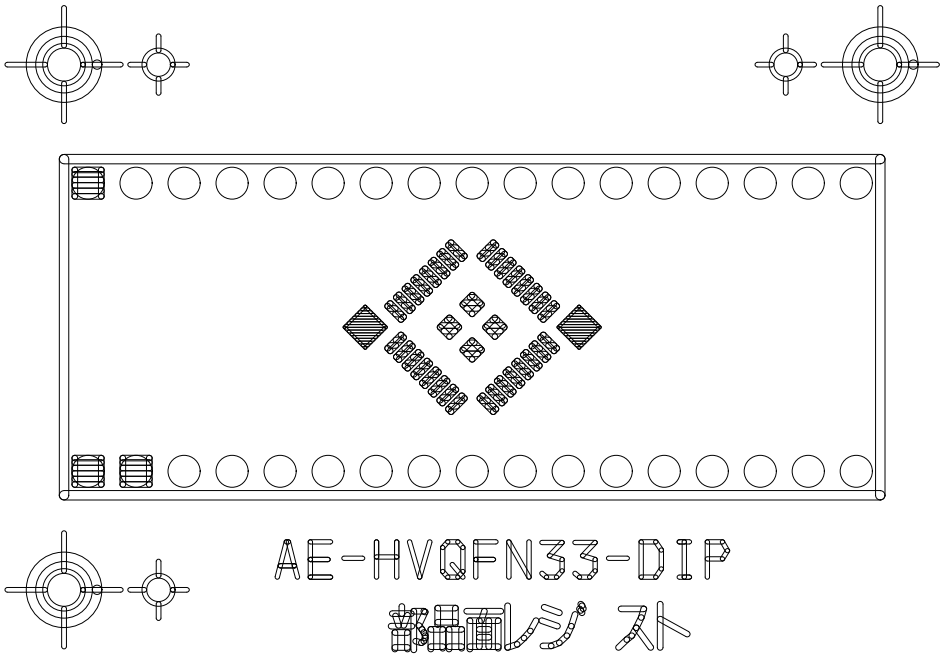


AE-HVQFN33-DIP 穴明加工図			
部品面透視図			
基板層数　2層板			
T. No	記号	穴径	穴数
T1	⊕	φ0.3 T.H 一般穴	20
T2	回	φ0.8 T.H 一般穴	34



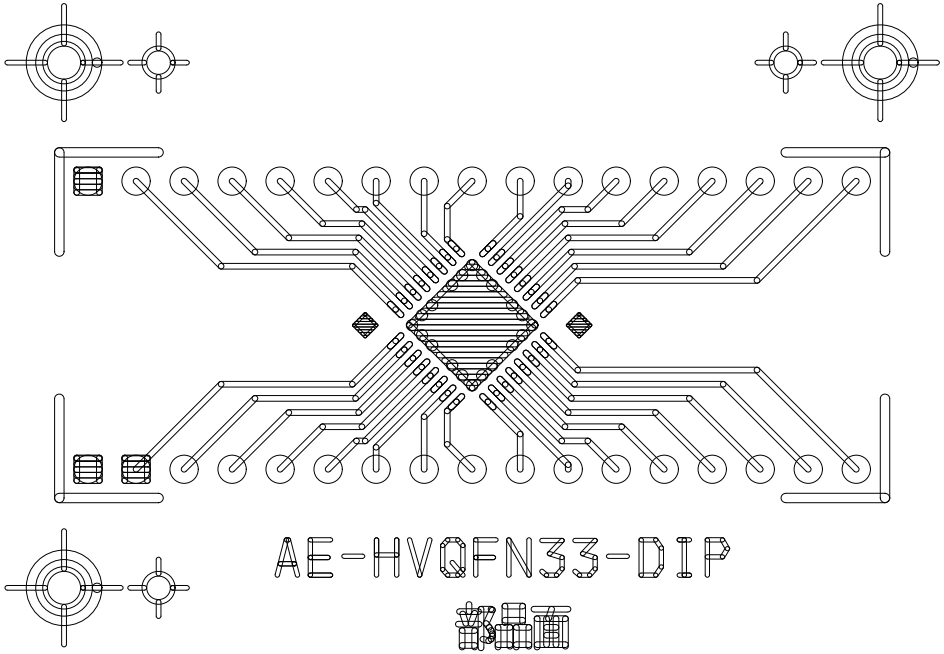
AE-HVQFN33-DIP
裏面メタルマスク


17
33
AE-HVQFN33-DIP
1
16
AE-HVQFN33-DIP
裏面シルク



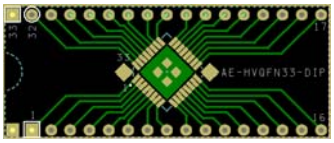
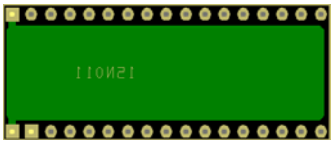
AE-HVQFN33-DIP

裏面レジスト


AE-HVQFN33-DIP

AE-HV0FN33-01P

AE-HV0FN33-DIP
半導体パッケージ
15N011


AE-HVQFN33-DIP